



Material Content Data Sheet



Sales Product Name		IPS80R1K2P7		Issued		24. January 2018		
MA#		MA001651868						
Package		PG-TO251-3-342		Weight*		317.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.666	0.52	0.52	5243	5243
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		464	
	non noble metal	copper	7440-50-8	147.096	46.28	46.34	462922	463525
	non noble metal	aluminium	7429-90-5	0.485	0.15	0.15	1526	1526
wire	non noble metal	aluminium	7429-90-5	0.485	0.15	0.15	1526	1526
encapsulation	organic material	carbon black	1333-86-4	1.420	0.45		4469	
	plastics	epoxy resin	-	24.850	7.82		78205	
	inorganic material	silicondioxide	60676-86-0	115.731	36.42	44.69	364213	446887
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11770	11770
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4470	4481
solder	non noble metal	tin	7440-31-5	0.039	0.01		123	
	noble metal	silver	7440-22-4	0.049	0.02		153	
	non noble metal	lead	7439-92-1	1.862	0.59	0.62	5861	6137
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60353	60431
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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